

Peltron[®]

Product Name	S-3021A/S-3021B
Product Category	Conductive Adhesive
Use	Car Electro Devices, General Modules, Die Attach, Touch Panel, Solar Battery
Function	Low Temperature Curing

Item	Condition	Unit	Typical Value
General Item			
Package	-	-	Pot
Liquid Feature			
Storage Stability	Part A : 10~25°C Part B : 0~10°C	-	Part A: 3 months Part B: 3 months
Cured Properties			
Recommended Curing Condition	Heat air circulation oven	-	25°C x 16 hours (120°C x 15 minutes)
Volume Resistivity	25°C x 16 hours cure	Ω·cm	8.0 x 10 ⁻⁴
Shear Adhesive Strength @25°C	4mm ² Si chip/FR-4 substrate	N/mm ²	8.7
	4mm ² Si chip/Al substrate		5.5
Characteristics	Low temperature (room temperature) curable conductive adhesive Suitable for use in case of no heat curing		

The above values are reference and not specification.



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